

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

Listing of Claims:

Claim 1 (Currently Amended): An electronic device connecting method comprising:
mounting an electrode of an electronic device closely on a sheet-like porous member having ~~a hole~~ pores, the porous member having a photosensitive layer, which produces or eliminates an ion exchange group by irradiation with energy beams[[,]] on [[a]] an inner surface ~~in the hole~~ of the ~~porous member~~ pores;

selectively irradiating a predetermined region of the porous member, on which the electronic device is mounted, with energy beams to form a latent image in an irradiated or non-irradiated portion of the porous member, the predetermined region including a portion close to the electrode;

after said selectively irradiating ~~with the energy beams~~, filling pores in the latent image of the porous member with a conductive material in a hole in the latent image of the porous member to form a conductive portion connected to the electrode; and

bonding the porous member, in which the conductive portion is formed by said filling, to the electronic device.

Claim 2 (Original): An electronic device connecting method as set forth in claim 1, wherein the mounting comprises pressure sensitive adhesion.

Claim 3 (Original): An electronic device connecting method as set forth in claim 1, wherein

the photosensitive layer produces or eliminates an ion exchange group in an irradiated or non-irradiated portion of the photosensitive layer of the porous member to form a pattern of an ion exchange group by the energy beams, and

the conductive portion is formed by selectively absorbing a conductive material or its precursor onto the pattern of the ion exchange group which is formed in the irradiated or non-irradiated portion of the photosensitive layer.

Claim 4 (Original): An electronic device connecting method as set forth in claim 3, further comprising;

electroless plating by using the conductive material or its precursor as a plating nucleus.

Claim 5 (Original): An electronic device connecting method as set forth in claim 1, wherein the conductive portion comprises a region which passes through the porous member, and a region which does not pass through the porous member.

Claim 6 (Original): An electronic device connecting method as set forth in claim 1, wherein the bonding comprises curing after a curing resin impregnates the porous member.

Claim 7-22 (Cancelled).